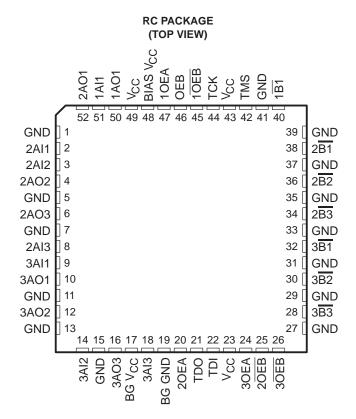
- Compatible With IEEE Std 1194.1-1991 (BTL)
- TTL A Port, Backplane Transceiver Logic (BTL) B Port
- Open-Collector B-Port Outputs Sink 100 mA
- BIAS V_{CC} Pin Minimizes Signal Distortion During Live Insertion or Withdrawal
- High-Impedance State During Power Up and Power Down
- B-Port Biasing Network Preconditions the Connector and PC Trace to the BTL High-Level Voltage
- TTL-Input Structures Incorporate Active Clamping to Aid in Line Termination



description

The SN74FB2041A is a 7-bit transceiver designed to translate signals between TTL and backplane transceiver logic (BTL) environments. The device is specifically designed to be compatible with IEEE Std 1194.1-1991.

The \overline{B} port operates at BTL signal levels. The open-collector \overline{B} ports are specified to sink 100 mA. Two output enables (OEB and \overline{OEB}) are provided for the \overline{B} outputs. When OEB is high and \overline{OEB} is low, the \overline{B} port is active and reflects the inverse of the data present at the A-input pins. When OEB is low, \overline{OEB} is high, or V_{CC} is less than 2.1 V, the \overline{B} port is turned off. The enable/disable logic partitions the device as two 3-bit sections and one 1-bit section.

The A port operates at TTL signal levels and has split input and output pins. The A outputs reflect the inverse of the data at the \overline{B} port when the A-port output enable (OEA) is high. When OEA is low or when V_{CC} is less than 2.1 V, the A outputs are in the high-impedance state.



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description (continued)

The pins TMS, TCK, TDI, and TDO are nonfunctional, i.e., not intended for use with the IEEE Std 1149.1 (JTAG) test bus. TMS and TCK are not connected and TDI is shorted to TDO.

BIAS V_{CC} establishes a voltage between 1.62 V and 2.1 V on the BTL outputs when V_{CC} is not connected.

ORDERING INFORMATION

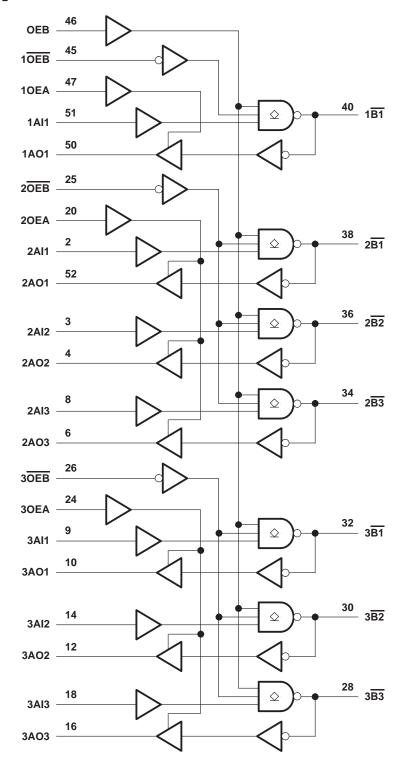
TA	PACKAGE [†]			TOP-SIDE MARKING	
0°C to 70°C	QFP – RC	Tube	SN74FB2041ARC	FB2041A	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

	INPUTS		FUNCTION				
OEB	OEB	OEA	FUNCTION				
L	Χ	L	Isolation				
Х	Н	L	isolation				
L	Χ	Н	<u> </u>				
Х	Н	Н	B data to AO bus				
Н	L	L	Al data to B bus				
Н	L	Н	Al data to B bus, B data to AO bus				

functional block diagram





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	\dots –0.5 V to 7 V
Input voltage range, V _I : Except B port	\dots –1.2 V to 7 V
B port	–1.2 V to 3.5 V
Voltage range applied to any \overline{B} output in the disabled or power-off state, V_0	\dots –0.5 V to 3.5 V
Voltage range applied to any output in the high state, V _O : A port	-0.5 V to V _{CC}
Input clamp current, I _{IK} : Except \overline{B} port	–40 mA
B port	–18 mA
Current applied to any single output in the low state, IO: A port	48 mA
B port	200 mA
Package thermal impedance, θ _{JA} (see Note 1)	44°C/W
Storage temperature range, T _{stq}	. -65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 2)

			MIN	NOM	MAX	UNIT
V _{CC} , BIAS V _{CC} , BG V _{CC}	Supply voltage		4.5	5	5.5	V
V	B pc		1.62		2.3	V
VIH	High-level input voltage	Except B port	2			
\/	Low lovel input veltage	B port	0.75		1.47	V
VIL	Low-level input voltage Excep				0.8] ' '
ΙΚ	Input clamp current				-18	mA
loн	High-level output current	AO port			-3	mA
la.	Low lovel output ourrent	AO port			24	A
IOL	Low-level output current B port				100	mA
TA	Operating free-air temperature		0		70	°C

NOTE 2: To ensure proper device operation, all unused inputs must be terminated as follows: A and control inputs to V_{CC}(5 V) or GND, and B inputs to GND only. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST	TEST CONDITIONS			MAX	UNIT
Viva	B port	V _{CC} = 4.5 V,	I _I = -18 mA			-1.2	V
ΛIK	Except B port	V _{CC} = 4.5 V,	$I_I = -40 \text{ mA}$			-0.5	V
Vон	AO port	V _{CC} = 4.5 V,	$I_{OH} = -3 \text{ mA}$	2.5	3.3		V
	AO port	V _{CC} = 4.5 V,	$I_{OL} = 24 \text{ mA}$		0.35	0.5	
V_{OL}	<u> </u>	V _{CC} = 4.5 V	$I_{OL} = 80 \text{ mA}$	0.75		1.1	V
	B port	VCC = 4.5 V	$I_{OL} = 100 \text{ mA}$			1.15	
lį	Except B port	V _{CC} = 5.5 V,	V _I = 5.5 V			50	μΑ
I _{IH} ‡	Except B port	V _{CC} = 5.5 V,	V _I = 2.7 V			50	μΑ
. +	Except B port	V _{CC} = 5.5 V,	V _I = 0.5 V			-50	
I _{IL} ‡	B port	V _{CC} = 5.5 V,	V _I = 0.75 V			-100	μΑ
IOH	B port	$V_{CC} = 0 \text{ to } 5.5 \text{ V},$	V _O = 2.1 V			100	μΑ
lozh	AO port	V _{CC} = 5.5 V,	V _O = 2.7 V			50	μΑ
lozL	AO port	V _{CC} = 5.5 V,	V _O = 0.5 V			-50	μА
lozpu	AO port	$V_{CC} = 0 \text{ to } 2.1 \text{ V},$	$V_0 = 0.5 \text{ V to } 2.7 \text{ V}$			50	μΑ
lozpd	AO port	$V_{CC} = 2.1 \text{ V to } 0,$	$V_0 = 0.5 \text{ V to } 2.7 \text{ V}$			-50	μΑ
los§	AO port	V _{CC} = 5.5 V,	V _O = 0	-30		-180	mA
	Al port to B port	V 55V	1 0			45	Δ
ICC	B port to AO port	V _{CC} = 5.5 V,	IO = 0			65	mA
0	Al port	V 05V = 05V		3			
Ci	Control inputs	V _I = 0.5 V or 2.5 V	3			pF	
Co	AO port	V _O = 0.5 V or 2.5 V			5.5		pF
	B port per	V _{CC} = 0 to 4.5 V				5	n.E
Cio	IEEE Std 1194.1-1991	V _{CC} = 4.5 V to 5.5 V				5	pF

live-insertion specifications over recommended operating free-air temperature range

PAR	AMETER	TEST CONDITIONS				MAX	UNIT
I _{CC} (BIAS V _{CC})		V _{CC} = 0 to 4.5 V	V0 to 2 V			450	μA
I.GC (PI)	42 AGG)	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	$V_B = 0 \text{ to } 2 \text{ V},$	V_I (BIAS V_{CC}) = 4.5 V to 5.5 V		10	μΑ
Vo	B port	$V_{CC} = 0$,	V _I (BIAS V _{CC}) = 5 V	1.62	2.1	V	
		$V_{CC} = 0$,	$V_B = 1 V$,	V_I (BIAS V_{CC}) = 4.5 V to 5.5 V	-1		
lo	B port	$V_{CC} = 0 \text{ to } 5.5 \text{ V},$	OEB = 0 to 0.8 V			100	μΑ
		$V_{CC} = 0 \text{ to } 2.2 \text{ V},$	OEB = 0 to 5 V			100	

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. ‡ For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current. § Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

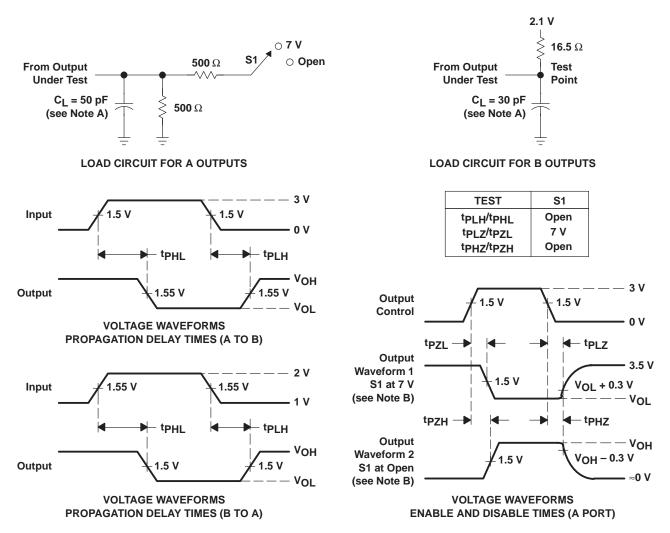
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switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5 V,$ $T_{A} = 25^{\circ}C$			MIN	MAX	UNIT
	(1141 01)	(0011 01)	MIN	TYP	MAX			
^t PLH	Al	B	2.3	3.9	5.1	2	5.6	ns
t _{PHL}	Al	В	2.6	4.1	5	2.5	5.3	115
^t PLH	ΒI	AO	2	3.6	4.8	1.7	5.3	ns
^t PHL	Б	AO	2.3	3.8	4.9	2	6.4	115
^t PLH	OEB	B	3	4.6	5.8	2.6	6.3	ns
t _{PHL}	OLB	В	3.1	4.7	6	3.1	6.2	
^t PLH	OEB	- B	2.7	4.3	5.6	2.6	5.8	ns
t _{PHL}	OEB	В	2.7	4.2	5.3	2.5	6.4	
^t PZH	OEA	AO	1.5	3.2	5.2	1.5	5.2	ns
^t PZL	OLA	AO	1.1	2.8	5	1	5	
t _{PHZ}	OEA	AO	1	2.4	3.9	1	4.2	ns ns
t _{PLZ}	OEA	AO	2.2	3.8	5.6	1.7	5.8	
t _{sk(p)} †	Pulse skew, AI to B or B to AC		0.5				ns	
t _{sk(o)} †	Output skew, Al to B or B to A		0.4				ns	
	Rise time, 1.3 V to 1.8 V, B outputs			1.6	2.4	1	2.5	
t _t	Fall time, 1.8 V to 1.3 V, B outputs			1 1.4	2.3	1	2.4	ns
t(pr)	B-port input pulse rejection					1		ns

[†] Skew values are applicable for through mode only.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: TTL inputs: PRR \leq 10 MHz, Z_O = 50 Ω , $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



PACKAGE OPTION ADDENDUM

6-Dec-2006

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp (3)
SN74FB2041ARC	ACTIVE	QFP	RC	52	96	TBD	CU SNPB	Level-2-240C-1YR
SN74FB2041ARCG3	ACTIVE	QFP	RC	52	96	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR
SN74FB2041ARCR	ACTIVE	QFP	RC	52	500	TBD	CU SNPB	Level-2-240C-1YR
SN74FB2041ARCRG3	ACTIVE	QFP	RC	52	500	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

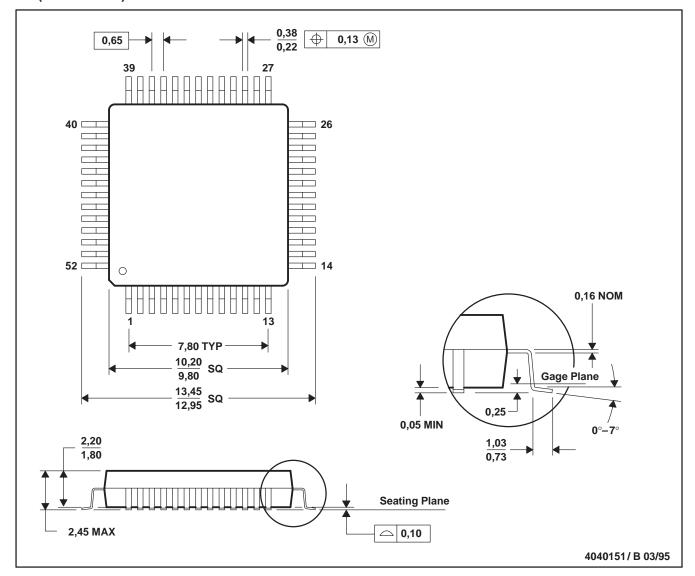
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1

RC (S-PQFP-G52)

PLASTIC QUAD FLATPACK



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-022

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